深圳市晶科鑫实业有限公司

样品承认书

客户代码：	
物料名称：	贴片钟振
规格型号：	SMD3225 OSC 6PIN 156.250MHZ 3.3V -40~85℃ HCSL
P N/ SJK：	3N156250G33HC
环保属性：	■RoHS ■REACH ■HF □PAHS □其它
版 次：	A1 2025-5-10 初版
湿敏等级：	一级

承 认 签 章					
供 应 商 承 认			（ ）公 司 承 认		
制定	审 核	核 准	工 程 师	审 核	批 准
贺丹斌	李相同	刘惠光			
SJK 支持			盖章签署		
FAE_EMAIL			日 期		
日 期					
备注：					

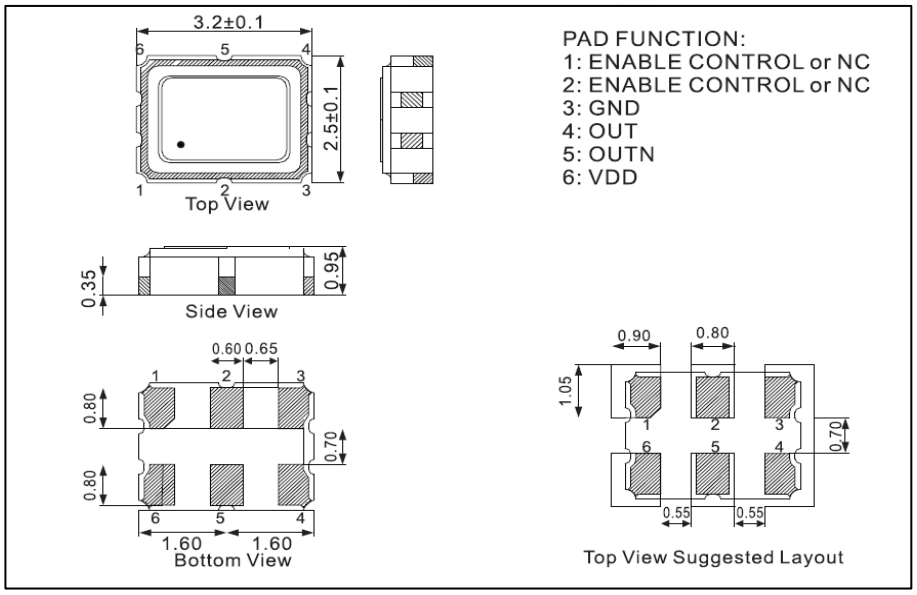
FEATURE

- Fundamental / 3rd overtone solution.
- 3.3V and 2.5V operation available.
- LVDS output, output frequencies 25 MHz to 200 MHz.
- Excellent low phase noise and jitter.
- Tri-State function available.
- Applications : Fibre Channel, Gigabit Ethernet, Serial ATA,
- Serial Attached SCSI, PCI-Express, SDH/SONET.
- RoHS Compliant / Pb Free.

ELECTRICAL SPECIFICATIONS

Parmeters	Condition\Model	3N
Fan Out Type		HCSL
Supply Voltage		3.3V±10%
Frequency		156.250MHz
Operating Temperature		-40℃ to +85℃
Current		60mA Typ.
Frequency Stability	All Conditions	±30ppm
Output Voltage (Rp=50Ω，Rs=33Ω，CL=2pF)	Vol	-0.15V min/0.15V max
	VoH	0.66V min/0.85V max
Rise/Fall Time	20%~80%	0.5ns max
Load Capacitance		15pF
Duty Cycle		50±10%
Storge Temperature		-55~+125℃
Start-upTime		10ms max
Output Load		100Ω
Aging		±3ppm (first year at 25℃)
Tri-State	Output Active	0.7VDD Min Pin 1 Tri-state
	Output in High-Impedance state	0.3VDD Max
Jitter	12kHz to 20MHz	0.2ps

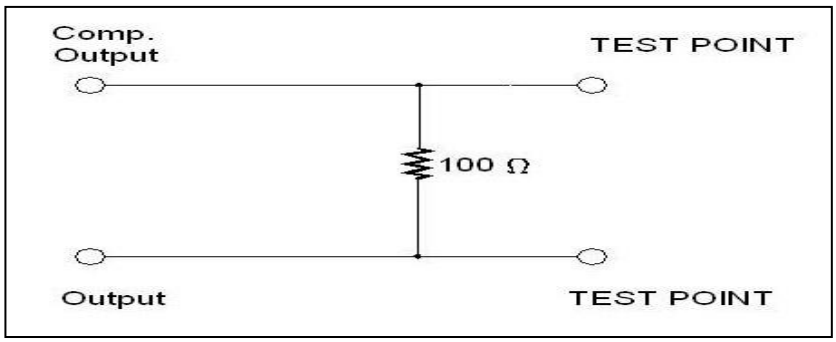
DIMENSION（Unit：mm）



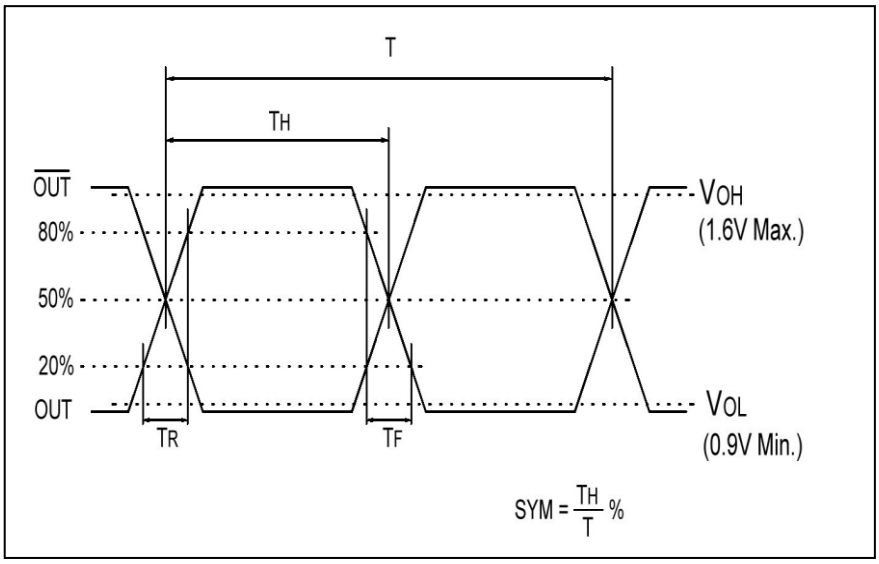
MARK



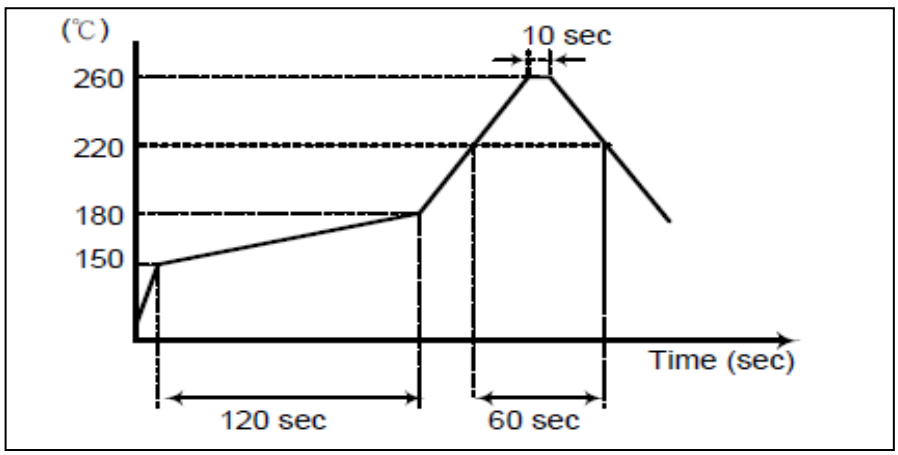
MEASUREMENT CIRCUIT



WAVEFORM CONDITIONS

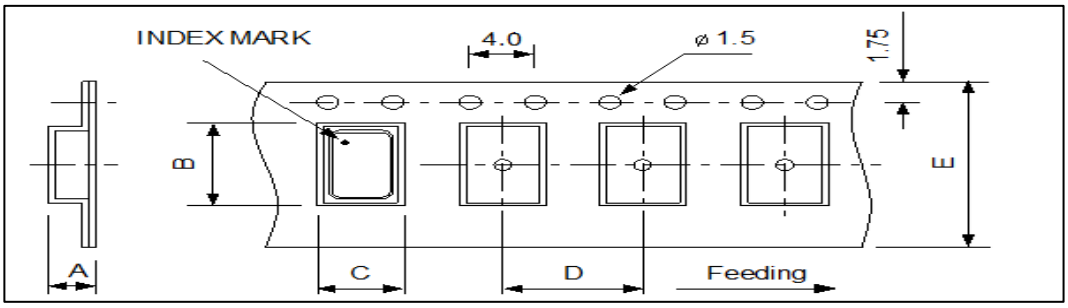


REFLOW CONDITION

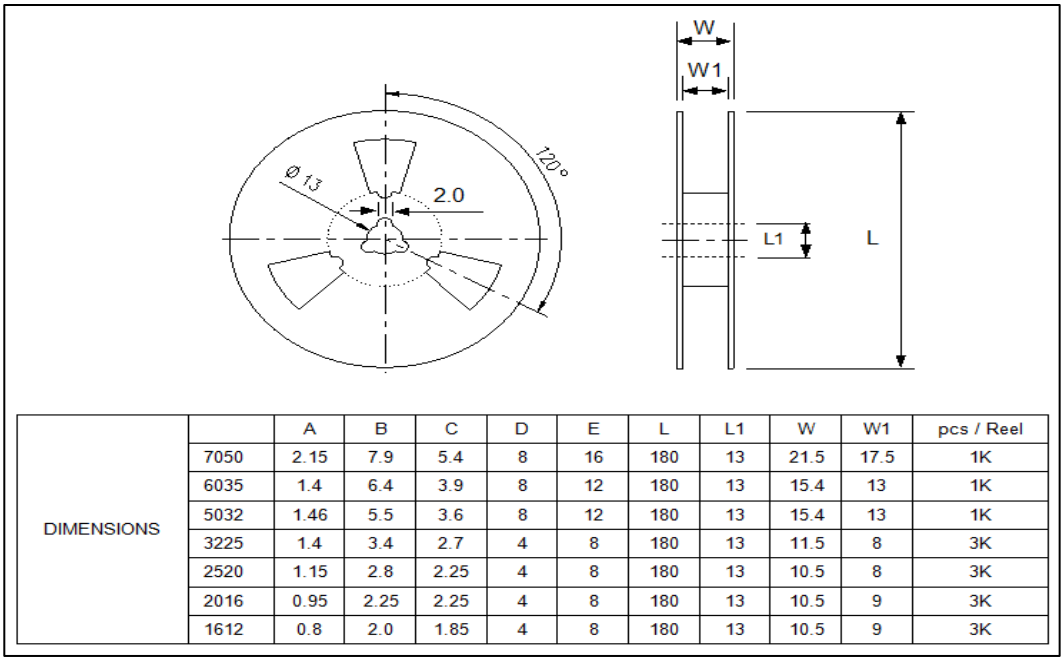


The reflow temperature profile may vary depending on the product model, specifications and frequency range.Refer to the individual product specifications for details

CARRIER TYPE

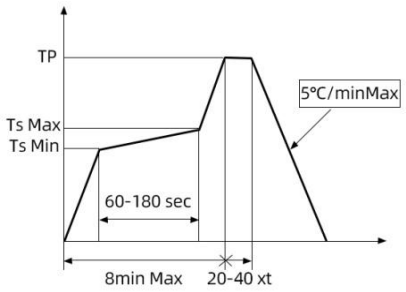


REEL



		A	B	C	D	E	L	L1	W	W1	pcs / Reel
DIMENSIONS	7050	2.15	7.9	5.4	8	16	180	13	21.5	17.5	1K
	6035	1.4	6.4	3.9	8	12	180	13	15.4	13	1K
	5032	1.46	5.5	3.6	8	12	180	13	15.4	13	1K
	3225	1.4	3.4	2.7	4	8	180	13	11.5	8	3K
	2520	1.15	2.8	2.25	4	8	180	13	10.5	8	3K
	2016	0.95	2.25	2.25	4	8	180	13	10.5	9	3K
	1612	0.8	2.0	1.85	4	8	180	13	10.5	9	3K

RELIABILITY TEST SPECIFICA TIONS

Test item	Equipment	Condition	Specification
1.SOLDERABILITY TEST	SJK-REL001、RC-328A	TP:260℃ TsMax：200℃ TsMin：150℃ 2 time 	MIL-STD-883E Method 2003.7
2. HERMETICITY TEST	HELIOT-306S	Pressurized 0.4~0.5Mpa ethanol sealed tank for 10 minutes	MIL-STD-883E Method 1014.10
3. VIBRATION TEST	HG-V4、S&A 250B	Enable Crystal(10g) from 10-55-10Hz,X、Y、Z horizontal,1 Minute vibration/time, 1time/ 2 hours.	MIL-STD-883E Method 2007.3
4. MECHANICAL SHOCK	HPC-200、S&A 250B	Enable Crystal 50G(490m/s2) time=11 ms speed=3.4 m/s half sine wave oscillation	JIS C6701
5. DROP TEST	HARD BOARD.S&A250B	75cm High,3 times on hard board	MIL-STD-202F Method 213B
6. HIGH&LOW TEMP STORAGE TEST(Static test)	H-PTH-80CK & HM101-3ABN，S&A 350B/250B	High temperature: 125℃±2 ℃,1000hr；Low temperature:-40℃±3 ℃,1000hrs	MIL-STD883C, METHOD 1011.8
7. TEMP &HUM CYCLING TEST	H-PTH-80CK CHAMBE，S&A 350B/250B	Temperature:-10℃±2 ℃～65℃±2 ℃,Humidity:93±3%,1 cycle need 24 hrs. 5cycles.	MIL-STD-883E Method 1005.8
8. HIGH TEM. & HUM.STORAGE TEST	H-PTH-80CK CHAMBE，S&A350B/250B	Temperature:85℃±2，Humidity:85+3,-2%,Store 96 hrs	JIS C6701
9. AGING TEST	H-PTH-80CK CHAMBE，S&A350B/250	Temperature:85℃±2，Store 1000 hrs	JIS C5023